

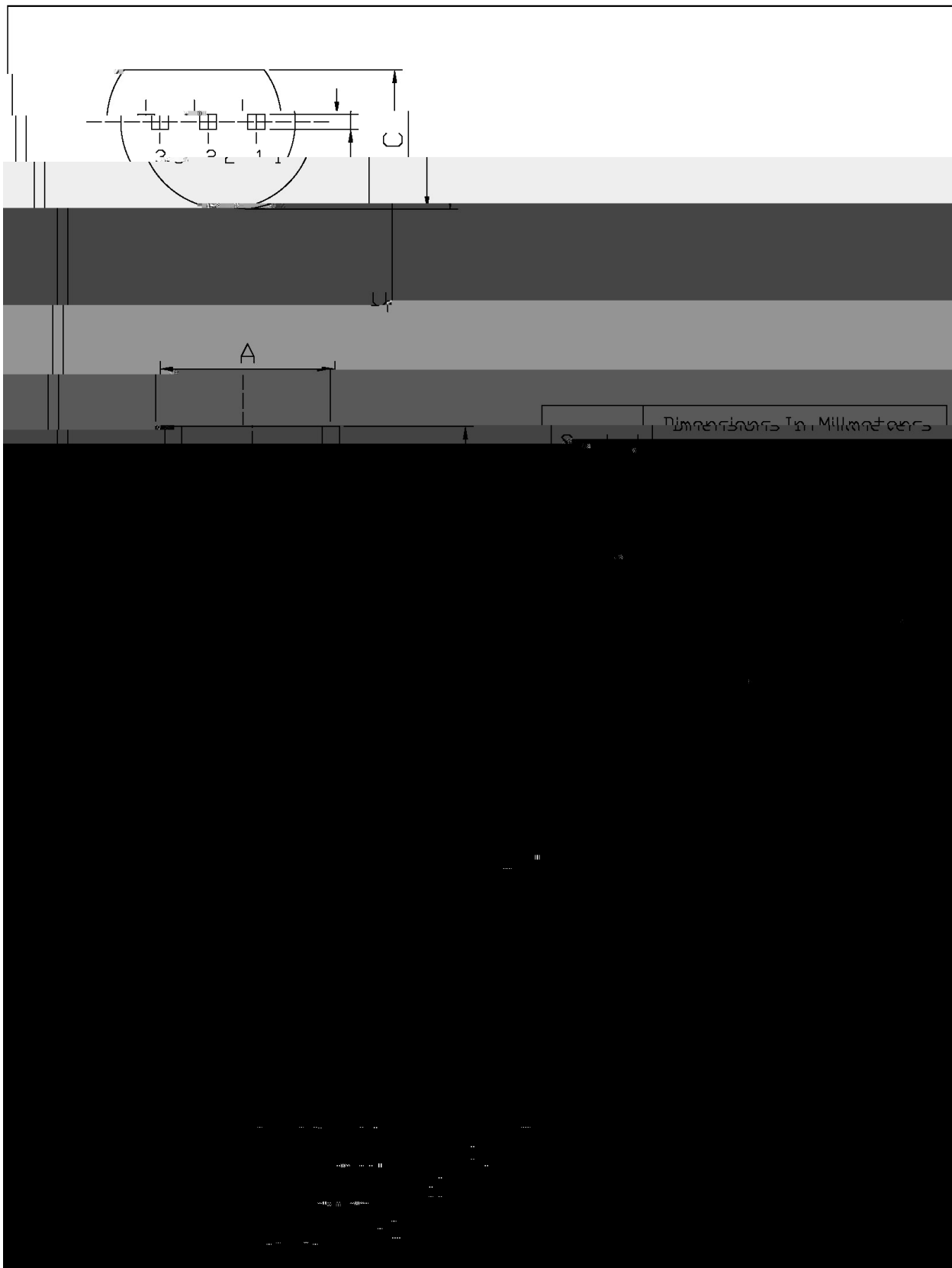
2SA298

Rev.E Mar.-2016

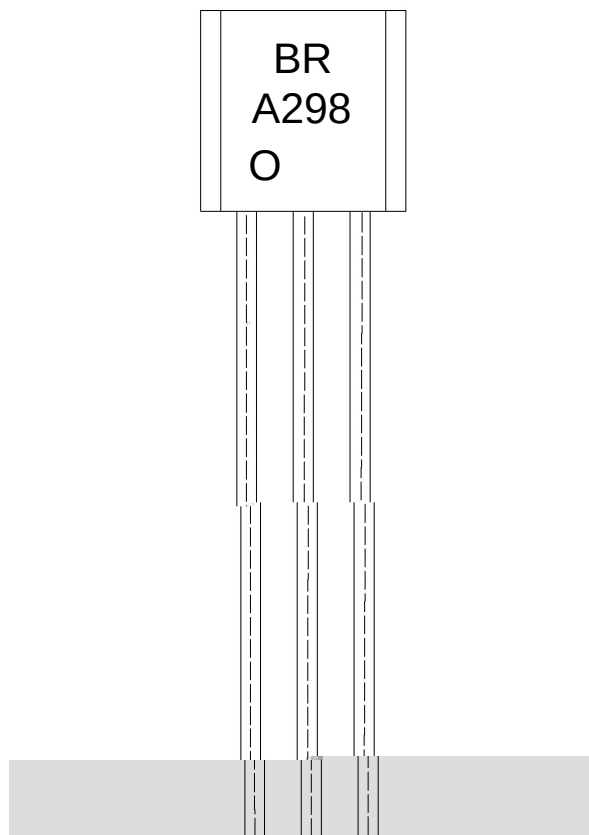
/ Package Dimensions

T0-92

Unit: mm



/ Marking Instructions



б " X

EU: № з " ПД

D5<; X № з " ПД

R: № h_{FE} ' ° ПД

---- X № 1 F њ " ПД 1 8 1 F њ " Ψ ρ

Note:

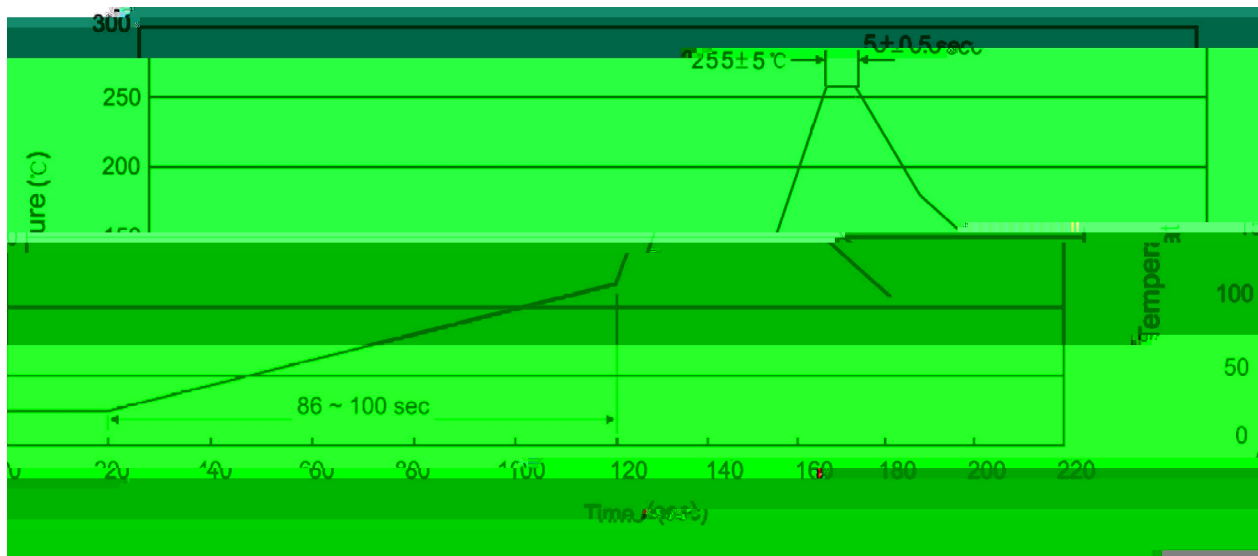
BR: Company Code.

A298: Product Type.

O: h_{FE} Classifications Symbol

****: Lot No. Code,code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



说明

1. 预加热: 25~150℃, Time: 60~90sec;
2. 峰值温度: 255±5℃, Time: 5~0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.
2. Peak Temp.: 255±5℃, Duration: 5~0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度: 270±5℃, Time: 10±1 sec. Temp: 270±5 Time: 10±1 sec

/ Packaging SPEC.

包装形式 / BULK

Package Type	Units					Dimension		(unit mm3)